

TR 50.4.25 Manual Hot Melt Bead Applicator



The TR 50.4.25 works with granulate, chip or wafer, and stick formed hot melt adhesives.

The mechanical thermostat temperature control is set to the required level by a simple adjustment on the side of the applicator. You can adjust the temperature from 20°C to 200°C to suit the specific adhesive being used..

Simple rear loading allows for quick recharging of the adhesive chamber, with either new or premelted product.

Various nozzles, balancers, stationary and manual stands, and pre-melting units are available to meet individual requirements.

Technical Data for TR 50.4.25

NOTE: All specifications are adhesive dependent

Voltage	115V, 400W
Air Pressure Required	20-100 psi
Temperature Control	Thermostat
Overheat protection	Thermal
Heat-up time, approx.	3-10 minutes
Tank capacity	250 grams
Extrusion rate, max. per minute	250 g/min
Electrical cord length	8.5 meters
Weight of handgun	1200 grams

Adhesive Application Specialists